

RECOMMENDED GLUES

The glues listed below are recommendations only and LEDIL advises the customer to test the suitability of the glue with each product.

MCPCB/FR4 CIRCUIT BOARDS

Loctite 460

Color: Transparent
Component: One component glue
Viscosity: Medium

Thermal resistance: Installation temperature +20°C - +28°C
Application temperature -50°C - +80°C
(momentarily also over +80°C)

Strength: More information about performance with different materials can be found on the datasheet

Curing time: At least 24 hours to obtain full strength, depending on the ambient conditions

Other: Does not absorb into acryl
Mild odour

More information on the datasheet (<http://www.ledil.com/datasheets/Loctite460.pdf>)

Hysol 9483

Color: Transparent
Component: Two component glue
Viscosity: Low

Thermal resistance: Installation temperature +20°C - +28°C
Application temperature -50°C - +150°C (momentarily also over +150°C)

Strength: More information about performance with different materials can be found on the datasheet

Curing time: Approximately 72 hours in room temperature (+22°C), depending on the ambient conditions and the amount of the glue used.

Other: Does not absorb into acryl

More information on the datasheet (<http://www.ledil.com/datasheets/Hysol9483.pdf>)

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CERAMIC CIRCUIT BOARDS**TEROSTAT MS 939**

Color:	White, off-white, grey & black
Component:	One component Adhesive/Sealant
Viscosity:	High
Thermal resistance:	Installation temperature +5°C - +40°C Application temperature -40°C - +100°C (momentarily also over +120°C)
Strength:	More information about performance with different materials can be found on the datasheet
Curing time:	3mm/24h
Other:	Does not absorb into acryl Odourless Suitable for flexible bonds

More information on the datasheet (<http://www.ledil.com/datasheets/Teroson939.pdf>)

GENERAL INSTRUCTIONS OF USE

All surfaces where glue is applied must be clean, dry and free from grease and dirt. If cleaning is needed, we recommend Propan-2-ol (IPA). Apply the glue only on the bond area (avoid contact with optical surfaces).

Remember to ensure the compatibility of the different substrates. Note that humidity and temperature fluctuation slow down the curing process and shorten the lifetime of the bond.